



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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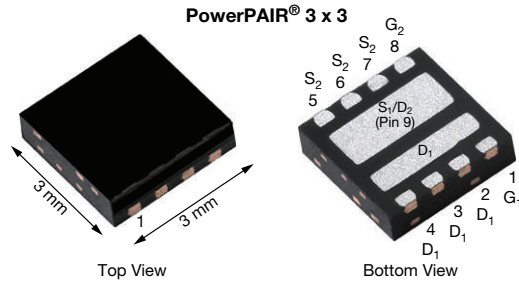
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Dual N-Channel 25 V (D-S) MOSFETs



FEATURES

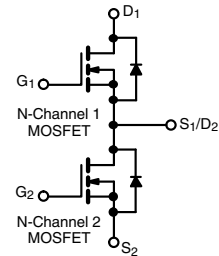
- TrenchFET® Gen IV power MOSFETs
- 100 % R_g and UIS tested
- Optimized Q_{gs}/Q_{gs} ratio improves switching characteristics
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- CPU core power
- Computer / server peripherals
- POL
- Synchronous buck converter
- Telecom DC/DC



PRODUCT SUMMARY		
	CHANNEL-1	CHANNEL-2
V _{DS} (V)	25	25
R _{DS(on)} max. (Ω) at V _{GS} = 10 V	0.00830	0.00424
R _{DS(on)} max. (Ω) at V _{GS} = 4.5 V	0.01270	0.00658
Q _g typ. (nC)	4.3	7.9
I _D (A) ^{a, g}	30	40
Configuration	Dual	

ORDERING INFORMATION	
Package	PowerPAIR 3 x 3
Lead (Pb)-free and halogen-free	SiZ320DT-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	CHANNEL-1	CHANNEL-2	UNIT	
Drain-source voltage	V _{DS}	25	25	V	
Gate-source voltage	V _{GS}	+16, -12	+16, -12		
Continuous drain current (T _J = 150 °C)	I _D	T _C = 25 °C	30 ^a	40 ^a	A
		T _C = 70 °C	29.2 ^a	40 ^a	
		T _A = 25 °C	17.2 ^{b, c}	24.8 ^{b, c}	
		T _A = 70 °C	13.7 ^{b, c}	19.8 ^{b, c}	
Pulsed drain current (100 μs pulse width)	I _{DM}	80	120	A	
Continuous source drain diode current	I _S	T _C = 25 °C	13.9	25.8	A
		T _A = 25 °C	3.1 ^{b, c}	3.5 ^{b, c}	
Single pulse avalanche current	I _{AS}	12	18	mJ	
Single pulse avalanche energy	E _{AS}	7.2	16.2		
Maximum power dissipation	P _D	T _C = 25 °C	16.7	31	W
		T _C = 70 °C	10.7	20	
		T _A = 25 °C	3.7 ^{b, c}	4.2 ^{b, c}	
		T _A = 70 °C	2.4 ^{b, c}	2.7 ^{b, c}	
Operating junction and storage temperature range	T _J , T _{stg}	-55 to +150		°C	
Soldering recommendations (peak temperature) ^d		260			

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	CHANNEL-1		CHANNEL-2		UNIT
		TYP.	MAX.	TYP.	MAX.	
Maximum junction-to-ambient ^{b, f}	R _{thJA}	27	34	24	30	°C/W
Maximum junction-to-case (drain)	R _{thJC}	6	7.5	3.2	4	

Notes

- Package limited
- Surface mounted on 1" x 1" FR4 board
- t = 10 s
- See solder profile (www.vishay.com/doc?73257). The PowerPAIR is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state conditions is 69 °C/W for channel-1 and 64 °C/W for channel-2
- T_C = 25 °C



SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static								
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	Ch-1	25	-	-	V	
		V _{GS} = 0 V, I _D = 250 μA	Ch-2	25	-	-		
V _{DS} Temperature coefficient	ΔV _{DS} /T _J	I _D = 250 μA	Ch-1	-	17	-	mV/°C	
		I _D = 250 μA	Ch-2	-	16	-		
V _{GS(th)} Temperature coefficient	ΔV _{GS(th)} /T _J	I _D = 250 μA	Ch-1	-	4.2	-		
		I _D = 250 μA	Ch-2	-	4.5	-		
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	Ch-1	1.1	-	2.4	V	
		V _{DS} = V _{GS} , I _D = 250 μA	Ch-2	1.1	-	2.4		
Gate source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = +16 V, -12 V	Ch-1	-	-	100	nA	
			Ch-2	-	-	100		
Zero gate voltage drain current	I _{DSS}	V _{DS} = 25 V, V _{GS} = 0 V	Ch-1	-	-	1	μA	
		V _{DS} = 25 V, V _{GS} = 0 V	Ch-2	-	-	1		
		V _{DS} = 25 V, V _{GS} = 0 V, T _J = 55 °C	Ch-1	-	-	10		
		V _{DS} = 25 V, V _{GS} = 0 V, T _J = 55 °C	Ch-2	-	-	10		
On-state drain current ^b	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	Ch-1	15	-	-	A	
		V _{DS} ≥ 5 V, V _{GS} = 10 V	Ch-2	15	-	-		
Drain-source on-state resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 8 A	Ch-1	-	0.00690	0.00830	Ω	
		V _{GS} = 10 V, I _D = 10 A	Ch-2	-	0.00353	0.00424		
		V _{GS} = 4.5 V, I _D = 5 A	Ch-1	-	0.01010	0.01270		
		V _{GS} = 4.5 V, I _D = 8 A	Ch-2	-	0.00526	0.00658		
Forward transconductance ^b	g _{fs}	V _{GS} = 10 V, I _D = 8 A	Ch-1	-	45	-	S	
		V _{GS} = 10 V, I _D = 10 A	Ch-2	-	68	-		
Dynamic ^a								
Input capacitance	C _{iss}	Channel-1 V _{DS} = 12.5 V, V _{GS} = 10 V, f = 1 MHz	Ch-1	-	660	-	pF	
			Ch-2	-	1370	-		
Output capacitance	C _{oss}		Ch-1	-	230	-	pF	
			Ch-2	-	410	-		
Reverse transfer capacitance	C _{rss}		Channel-2 V _{DS} = 12.5 V, V _{GS} = 10 V, f = 1 MHz	Ch-1	-	35	-	pF
			Ch-2	-	55	-		
C _{rss} /C _{iss} ratio			Ch-1	-	0.056	0.115		
			Ch-2	-	0.04	0.08		
Total gate charge	Q _g		V _{DS} = 12.5 V, V _{GS} = 10 V, I _D = 15 A	Ch-1	-	9.5	15	nC
			V _{DS} = 12.5 V, V _{GS} = 10 V, I _D = 20 A	Ch-2	-	17.8	26.7	
		V _{DS} = 12.5 V, V _{GS} = 4.5 V, I _D = 15 A	Ch-1	-	4.3	8.9		
		V _{DS} = 12.5 V, V _{GS} = 4.5 V, I _D = 20 A	Ch-2	-	7.9	11.9		
Gate-source charge	Q _{gs}	Channel-1 V _{DS} = 12.5 V, V _{GS} = 4.5 V, I _D = 15 A	Ch-1	-	1.8	-	nC	
		Ch-2	-	3.8	-			
Gate-drain charge	Q _{gd}	Channel-2 V _{DS} = 12.5 V, V _{GS} = 4.5 V, I _D = 20 A	Ch-1	-	0.8	-	nC	
		Ch-2	-	1.2	-			
Output charge	Q _{oss}	V _{DS} = 12.5 V, V _{GS} = 0 V	Ch-1	-	4.6	-	nC	
			Ch-2	-	8.1	-		
Gate resistance	R _g	f = 1 MHz	Ch-1	0.26	1.3	2.6	Ω	
			Ch-2	0.2	1	2		



SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Dynamic ^a							
Turn-on delay time	t _{d(on)}	Channel-1 V _{DD} = 12.5 V, R _L = 1.25 Ω I _D ≅ 10 A, V _{GEN} = 10 V, R _g = 1 Ω	Ch-1	-	8	20	ns
			Ch-2	-	12	24	
Rise time	t _r	Channel-1 V _{DD} = 12.5 V, R _L = 1.25 Ω I _D ≅ 10 A, V _{GEN} = 10 V, R _g = 1 Ω	Ch-1	-	28	45	
			Ch-2	-	26	40	
Turn-off delay time	t _{d(off)}	Channel-2 V _{DD} = 12.5 V, R _L = 1.25 Ω I _D ≅ 10 A, V _{GEN} = 10 V, R _g = 1 Ω	Ch-1	-	15	25	
			Ch-2	-	20	30	
Fall time	t _f	Channel-2 V _{DD} = 12.5 V, R _L = 1.25 Ω I _D ≅ 10 A, V _{GEN} = 10 V, R _g = 1 Ω	Ch-1	-	10	20	
			Ch-2	-	10	20	
Turn-on delay time	t _{d(on)}	Channel-1 V _{DD} = 12.5 V, R _L = 1.25 Ω I _D ≅ 10 A, V _{GEN} = 4.5 V, R _g = 1 Ω	Ch-1	-	15	25	
			Ch-2	-	22	35	
Rise time	t _r	Channel-1 V _{DD} = 12.5 V, R _L = 1.25 Ω I _D ≅ 10 A, V _{GEN} = 4.5 V, R _g = 1 Ω	Ch-1	-	80	120	
			Ch-2	-	35	53	
Turn-off delay time	t _{d(off)}	Channel-2 V _{DD} = 12.5 V, R _L = 1.25 Ω I _D ≅ 10 A, V _{GEN} = 4.5 V, R _g = 1 Ω	Ch-1	-	10	20	
			Ch-2	-	10	20	
Fall time	t _f	Channel-2 V _{DD} = 12.5 V, R _L = 1.25 Ω I _D ≅ 10 A, V _{GEN} = 4.5 V, R _g = 1 Ω	Ch-1	-	38	57	
			Ch-2	-	17	26	
Drain-Source Body Diode Characteristics							
Continuous source-drain diode current	I _S	T _C = 25 °C	Ch-1	-	-	13.9	A
			Ch-2	-	-	25.8	
Pulse diode forward current (t = 100 μs)	I _{SM}		Ch-1	-	-	80	
			Ch-2	-	-	120	
Body diode voltage	V _{SD}	I _S = 8 A, V _{GS} = 0 V	Ch-1	-	0.83	1.2	V
		I _S = 10 A, V _{GS} = 0 V	Ch-2	-	0.81	1.2	
Body diode reverse recovery time	t _{rr}		Ch-1	-	26	52	ns
			Ch-2	-	34	68	
Body diode reverse recovery charge	Q _{rr}	Channel-1 I _F = 10 A, di/dt = 100 A/μs, T _J = 25 °C	Ch-1	-	26	52	nC
			Ch-2	-	30	60	
Reverse recovery fall time	t _a	Channel-2 I _F = 10 A, di/dt = 100 A/μs, T _J = 25 °C	Ch-1	-	14	-	ns
			Ch-2	-	18	-	
Reverse recovery rise time	t _b		Ch-1	-	12	-	
			Ch-2	-	16	-	

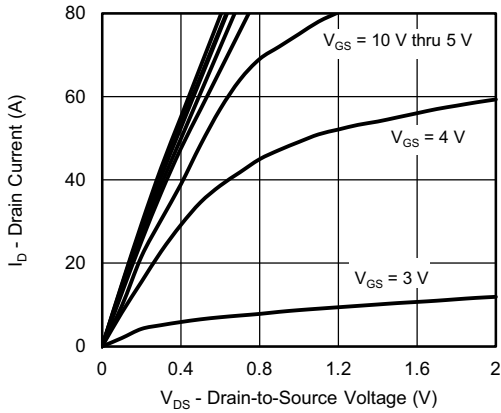
Notes

- a. Guaranteed by design, not subject to production testing
- b. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %

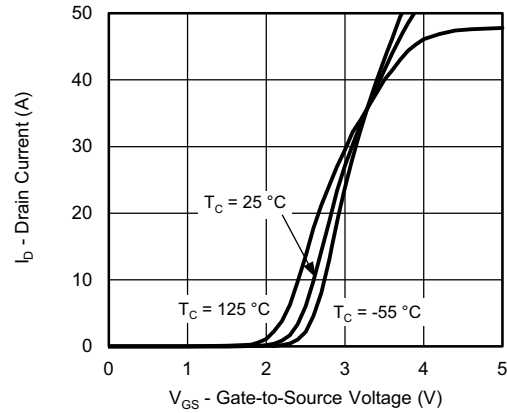
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



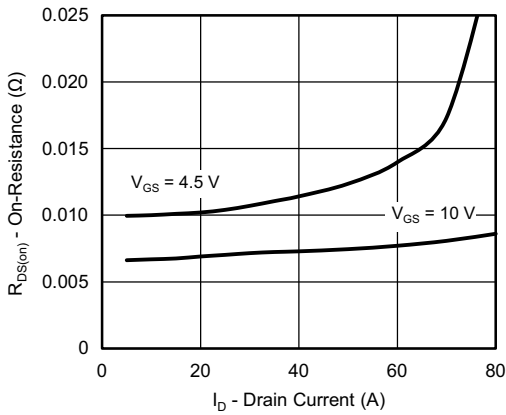
CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



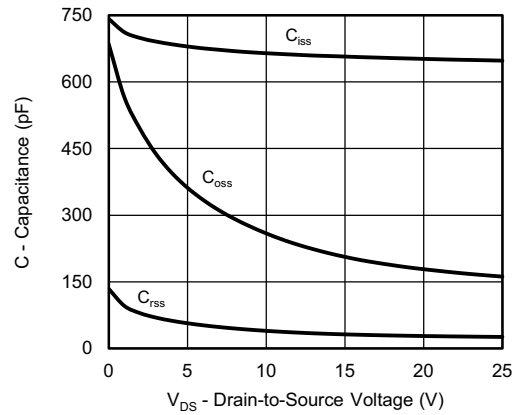
Output Characteristics



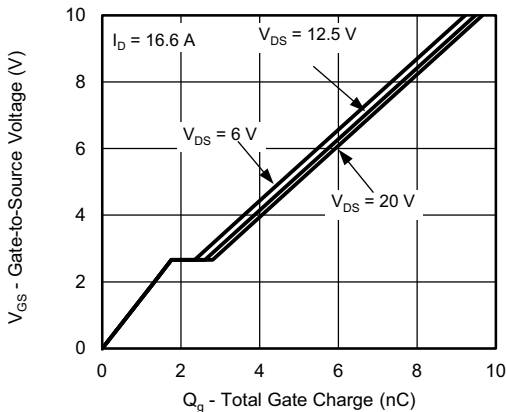
Transfer Characteristics



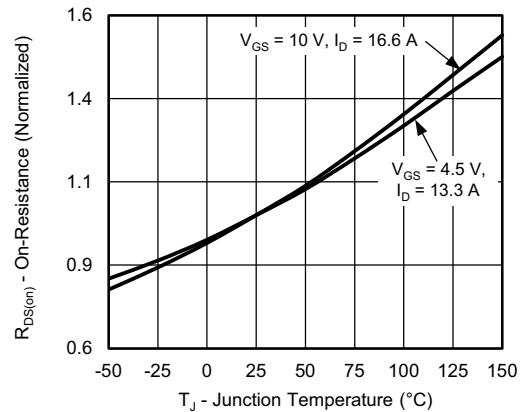
On-Resistance vs. Drain Current



Capacitance



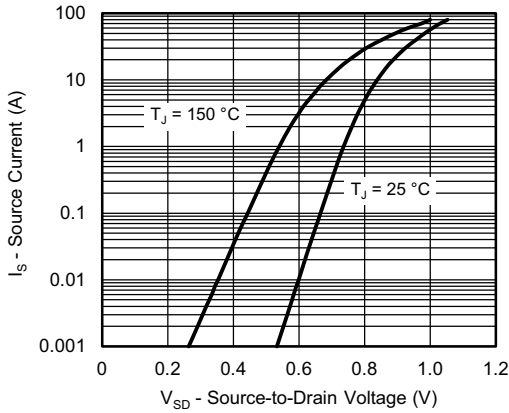
Gate Charge



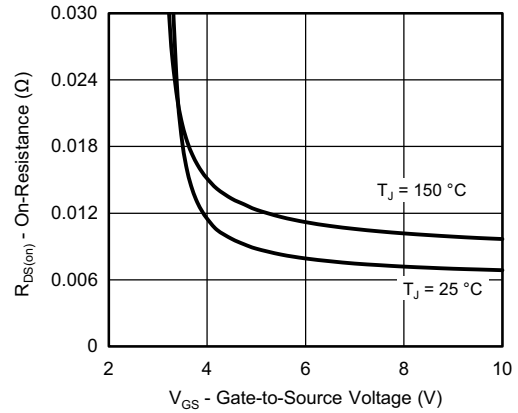
On-Resistance vs. Junction Temperature



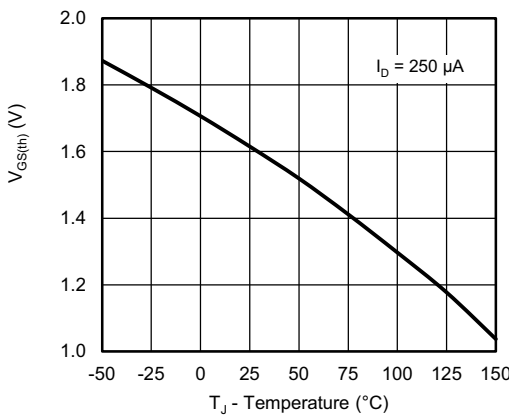
CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



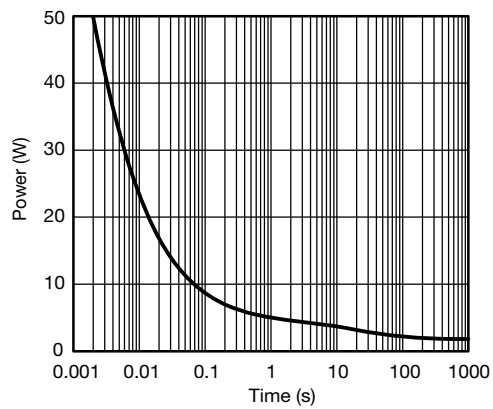
Source-Drain Diode Forward Voltage



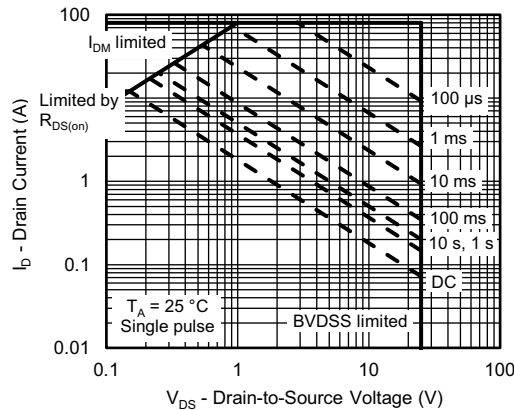
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient

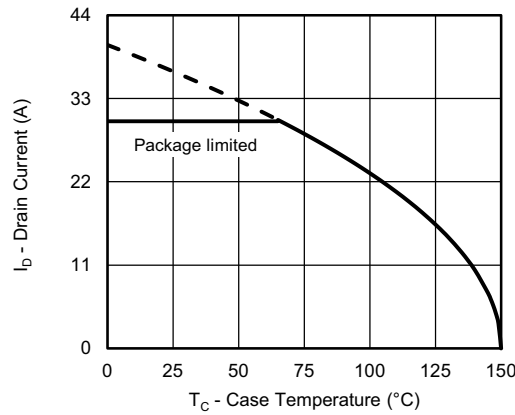


Safe Operating Area, Junction-to-Ambient

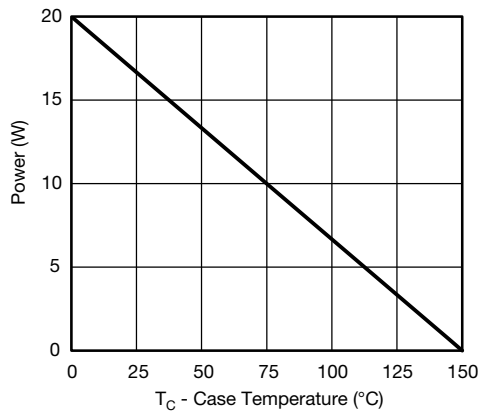
(1) $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified



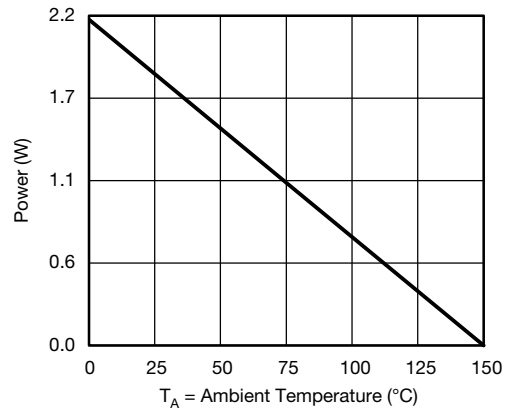
CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating ^a



Power, Junction-to-Case

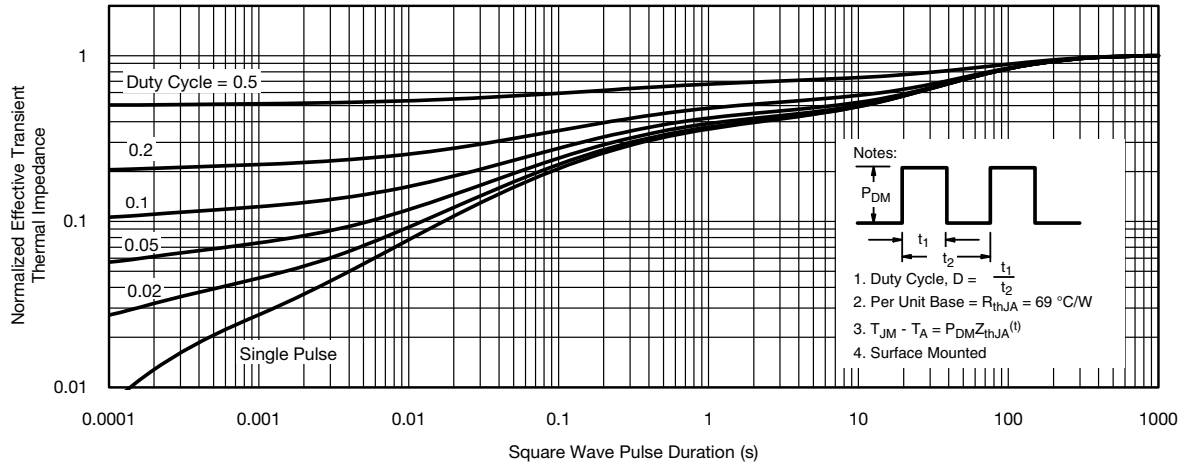


Power, Junction-to-Ambient

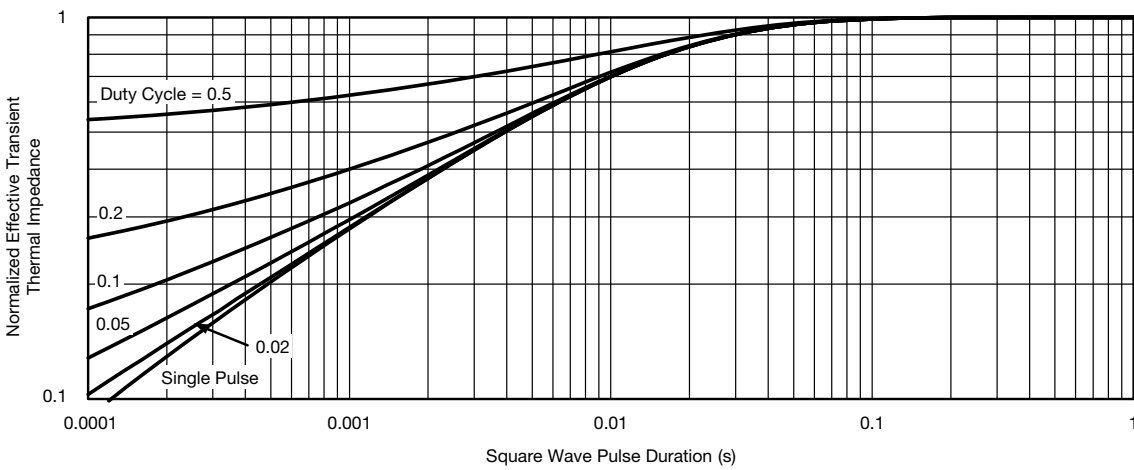
Note

- a. The power dissipation P_D is based on T_J max. = 25 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

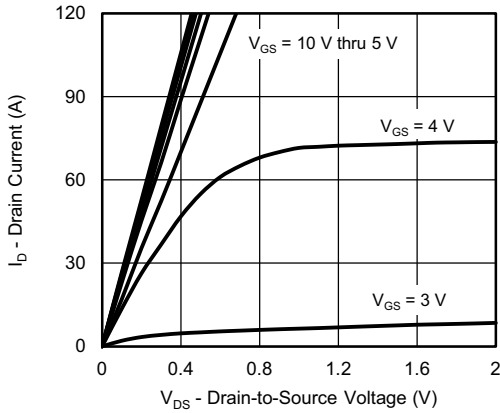


Normalized Thermal Transient Impedance, Junction-to-Ambient

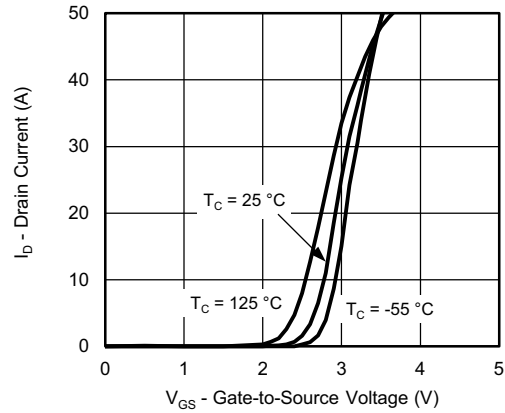


Normalized Thermal Transient Impedance, Junction-to-Case

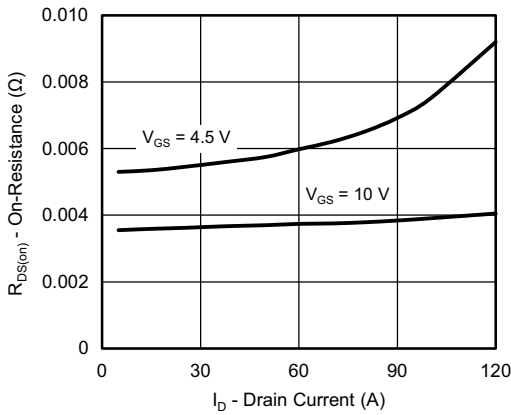
CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



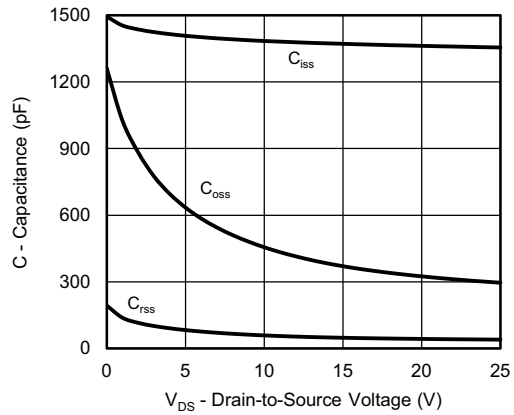
Output Characteristics



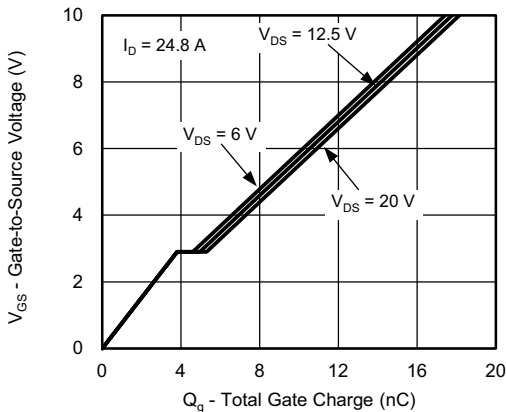
Transfer Characteristics



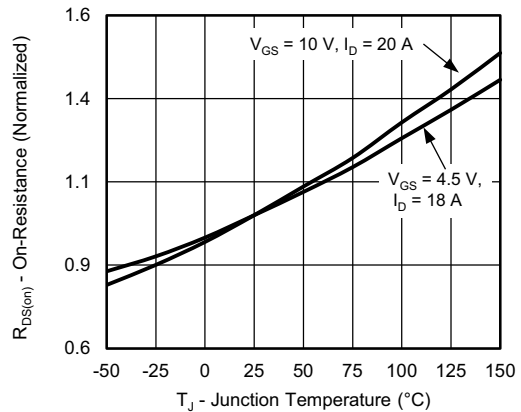
On-Resistance vs. Drain Current



Capacitance

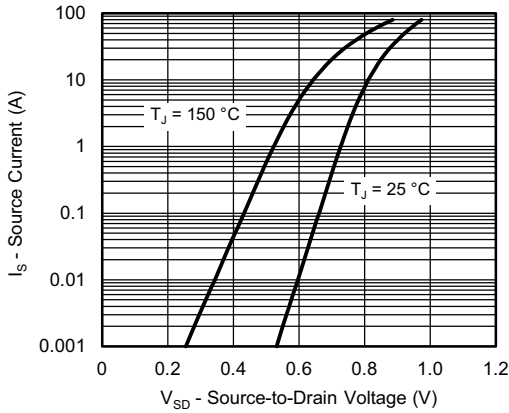


Gate Charge

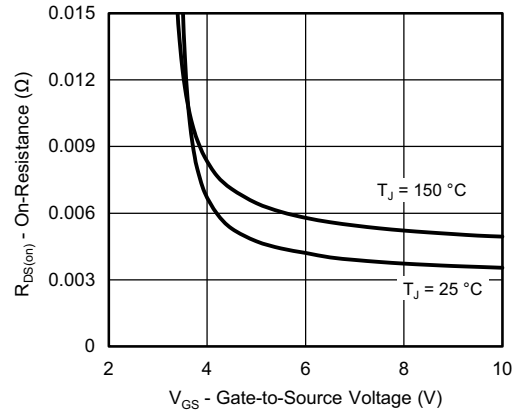


On-Resistance vs. Junction Temperature

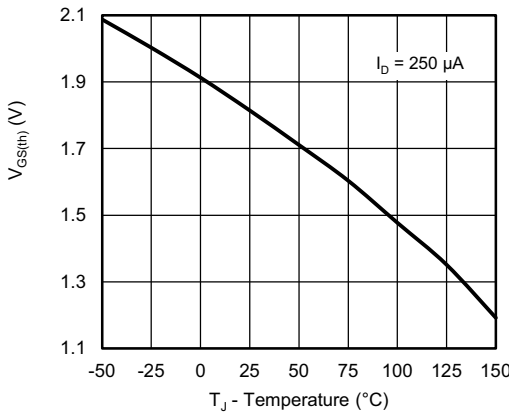
CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



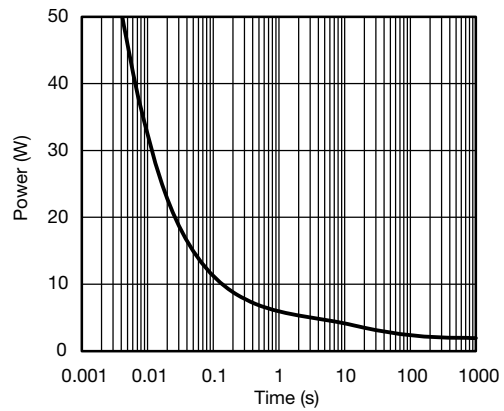
Source-Drain Diode Forward Voltage



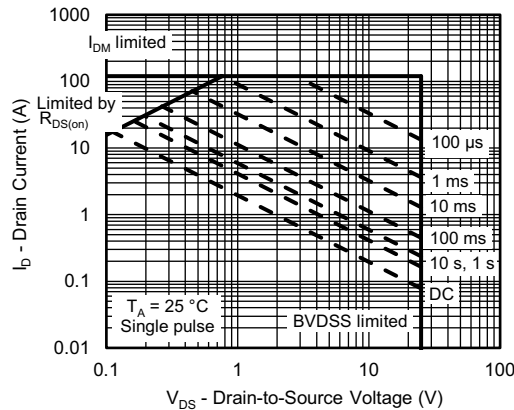
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient

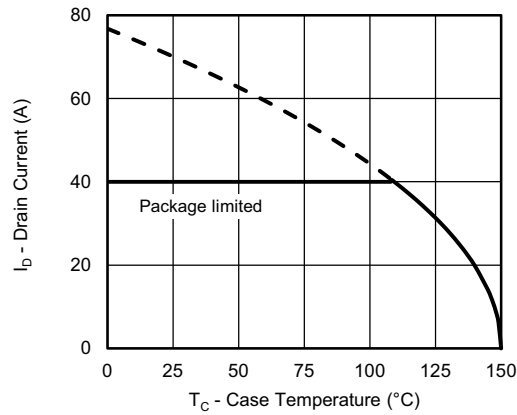


Safe Operating Area, Junction-to-Ambient

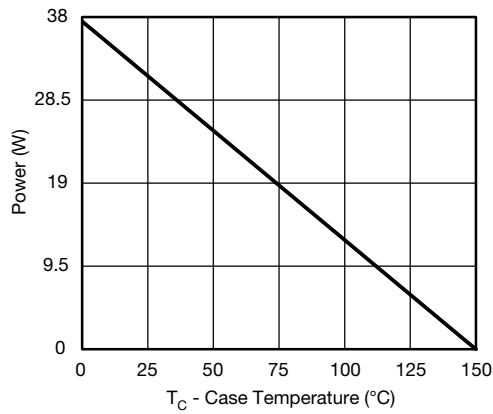
(1) $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified



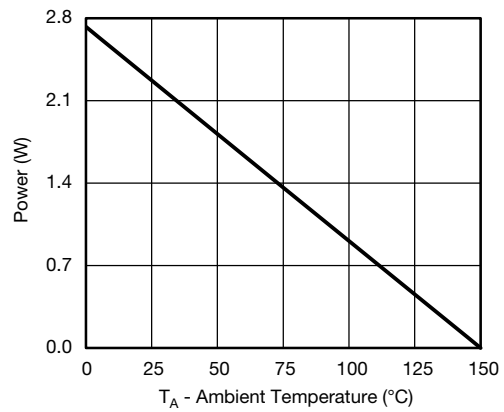
CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating ^a



Power, Junction-to-Case



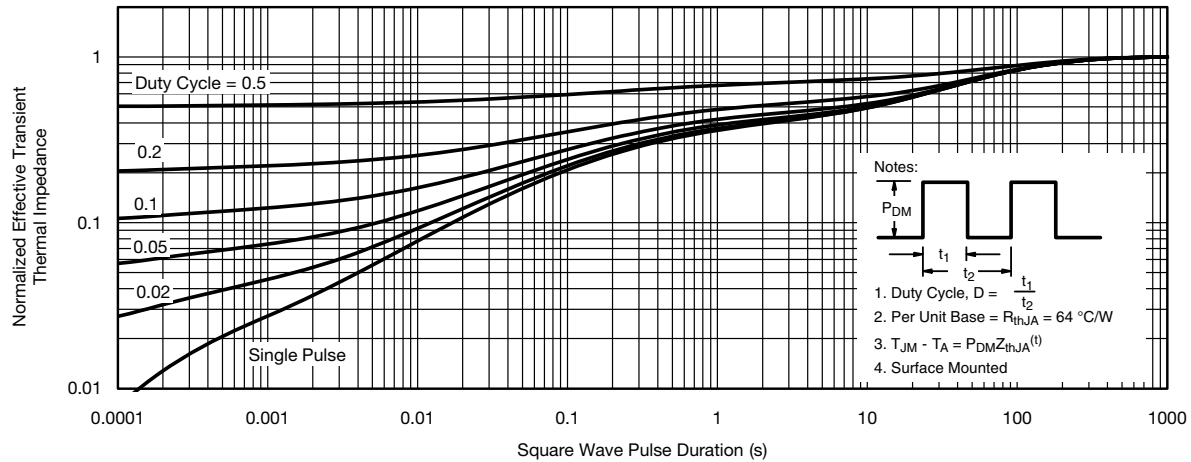
Power, Junction-to-Ambient

Note

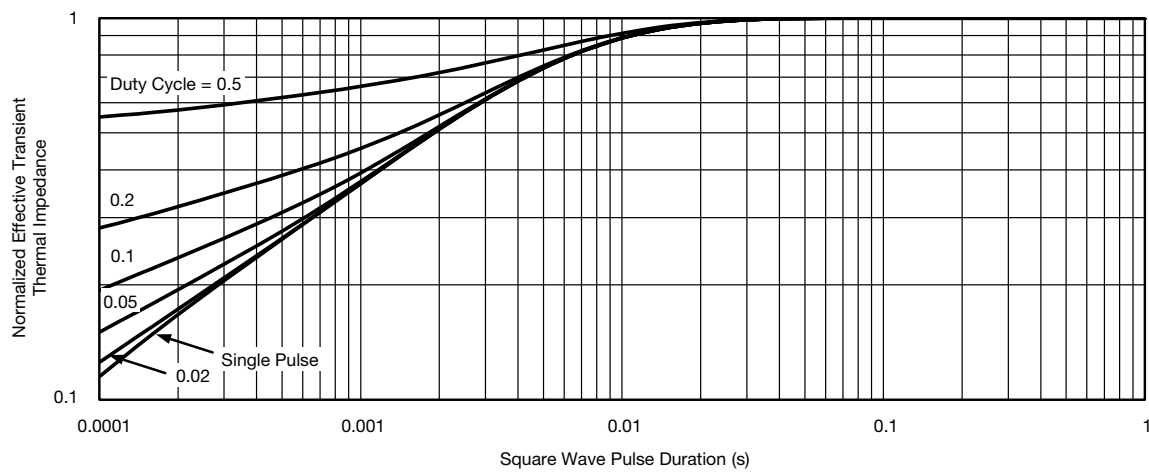
- a. The power dissipation P_D is based on T_J max. = 25 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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